#### N-Channel Enhancement Mode MOSFET

#### **Product Summary**

Vds	40V
ID(@TA=25°C)	156A
R <sub>DS(ON)</sub> (@Vgs=10V Id=20A)	≤1.9mΩ
R <sub>DS(ON)</sub> (@VGs=4.5V ID=20A)	≤2.5mΩ

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## Features

- Proprietary Trench Gate Device Design and Processes
- ♦ Low R<sub>DS(ON)</sub>
- 100% Avalanche Tested
- Reliable and Rugged
- RoHS complian

## **Applications**

- DC/DC Converter
- Battery Management System
- Industrial and Motor Drive applications
- Synchronous rectifier applications
- ♦ Half-bridge and full-bridge topologies

## Package Marking And Ordering information

Part Number	Package Type	Packaging	Reel(pcs)
UN0415N1R2-PD56	DFN5*6-8L	Tape & Reel	5,000

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## Absolute Maximum Ratings TC = $25^{\circ}$ C unless otherwise specified

Parameter		Symbol	Maximum	Units	
Drain to Source Voltage		VDs	40	V	
Continuous Drain Current <sup>1)</sup>	@TC=25°C	- ID -	156	А	
	@TC=100°C		99		
Drain Current Pulsed 2)		IDM	468	А	
Gate-Source Voltage		VGS	±20	V	
Single Pulsed Avalanche Energy <sup>3)</sup>		EAS	455	mJ	
Power Dissipation	@TC=25°C	PD	83	W	
	@TC=100°C		33		
Junction and Storage Temperature Range		Tstg,TJ	-55~150	Ĵ	

## **Thermal Characteristics**

Parameter	Symbol	Tay	Max	Units
Thermal Resistance from Junction to Ambient	ReJA		60	°C/W
Thermal Resistance, Junction to Case	ReJC		1.5	°C/W

Notes:

1) The maximum current rating is silicon wafer limited.

2) Single pulse width limited by junction temperature .

3) Limited by TJ(MAX), Starting at TJ=25°C, Rg=25 $\Omega$ , L=0.5mH.

4) Design parameters, Guaranteed by design, not subject to production.



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## Electrical Characteristics at Tc = $25^{\circ}$ C unless otherwise specified

Parameter	Symbol	Test Conditions	Min	Тур	Max	Units	
STATIC PARAMETERS							
Drain-Source Breakdown Voltage	BVdss	Vgs = 0V, ID = 250uA	40			V	
Drain-Source Leakage Current	IDSS	Vds = 40V , Vgs = 0V			1.0	μA	
Gate-source leakage current	lgss	Vgs = ±20V , Vds = 0V			±100	nA	
Gate-Source Threshold Voltage	Vgs(th)	Vgs = Vds , Id = 250µA	1.0	-	2.5	V	
Drain Source On State Posistance	Rds(on)	Vgs = 10V , Id = 20A		1.2	1.9	mΩ	
Drain-Source On-State Resistance	KDS(ON)	Vgs = 4.5V , Id = 20A		1.7	2.5	mΩ	
Forward Transconductance(GMP)	GFS	Vds = 5.0V, Id = 30A		62		S	
E	Body-Diode PARAMETERS						
Drain-Source Diode Forward Voltage	Vsd	Is = 1A, VGs = 0V		0.7	1.1	V	
Body Diode Reverse Recovery Time	trr	IF = 20A		53		ns	
Body Diode Reverse Recovery Charge	Qrr	di/dt = 100A/µs		82		nC	
	DYNAMIC	PARAMETERS <sup>4)</sup>					
Gate Resistance	Rg	F = 1MHZ		1.0		Ω	
Input Capacitance	Ciss	Vgs = 0V		9247		pF	
Output Capacitance	Coss	VDS = 20V		1455		pF	
Reverse Transfer Capacitance	Crss	F = 1MHz		1426		pF	
Gate charge Total	Qg	Vgs = 10V		125		nC	
Gate to Source Charge	Qgs	VDS = 20V		36.7		nC	
Gate to Drain Charge	Qgd	ID = 20A		35.2		nC	
SWITCHING PARAMETERS <sup>4)</sup>							
Turn-On Delay Time	td(on)			23.6		ns	
Turn-On Rise Time	tr	VDS = 20V, VGS = 10V		30.7		ns	
Turn-Off Delay Time	td(OFF)	Rg = 1.5Ω		76.2		ns	
Turn-Off Fall Time	tf			42.4		ns	

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## **Electrical Characteristics Curves**







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#### **Electrical Characteristics Curves**







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#### Fig. 10 Gate Charge Characteristics



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#### **Electrical Characteristics Curves**





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#### **Test Circuit**



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# N-Channel Enhancement Mode MOSFET

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## DFN5\*6-8L Package Outine & Dimensions (Units: mm / in)





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